

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	N/A	Silicon Carbide (SiC)	409-21-2	0.02	100.0	1.02
			<b>Subtotal</b>	<b>0.02</b>	<b>100</b>	<b>1.02</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0	100.0	0
			<b>Subtotal</b>	<b>0</b>	<b>100</b>	<b>0</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	1.2
	Copper alloy	Iron (Fe)	7439-89-6	0.07	0.1	3.99
	Copper alloy	Copper (Cu)	7440-50-8	67.17	99.87	3984.81
			<b>Subtotal</b>	<b>67.26</b>	<b>100</b>	<b>3990</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.1	6.5	124.34
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	5.16	16.0	306.08
	Filler	Silica fused	60676-86-0	22.89	71.0	1358.23
	Flame retardant	Metal hydroxide		2.1	6.5	124.34
			<b>Subtotal</b>	<b>32.25</b>	<b>100</b>	<b>1912.99</b>
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.37	100.0	22
			<b>Subtotal</b>	<b>0.37</b>	<b>100</b>	<b>22</b>
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0.01	5.0	0.33
	Lead alloy	Silver (Ag)	7440-22-4	0	2.5	0.16
	Lead alloy	Lead (Pb)	7439-92-1	0.1	92.5	6.01
			<b>Subtotal</b>	<b>0.11</b>	<b>100</b>	<b>6.5</b>
			<b>Total</b>	<b>100.01</b>	<b>100</b>	<b>5932.51</b>

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